

Abstract

Process for the multi-stage production of diffusion-brazed joins for power components with semiconductor chips

The invention relates to a process for the multi-stage production of diffusion-brazed joins (16, 17) for power components with semiconductor chips, the melting points of diffusion-brazing alloys (14, 15) and diffusion-brazed joins (16, 17) being staggered in such a manner that a first melting point of the first diffusion-brazing alloy (14) is lower than a second melting point of the second diffusion-brazing alloy (15), and the second melting point being lower than a third melting point of a first diffusion-brazed join (16) of the first diffusion-brazing alloy (14).

[Figure 1]